

Features

- Package in 8mm tape on 7" diameterreel
- Compatible with automatic placement equipment
- Compatible within frared and vapor phase reflows older process

The product itself will remain within RoHS compliant version

RS PRO LEDs

RS Stock No.: 0280104



RS PRO is the own brand of RS. The RS PRO Seal of Approval is your assurance of professional quality, a guarantee that every part is rigorously tested, inspected, and audited against demanding standards. Making RS PRO the Smart Choice for our customers.



Product Description

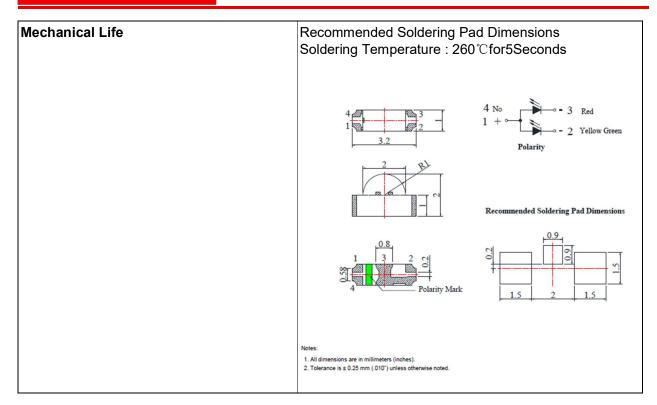
SMD LEDLED is much smaller than lead frame type component, higher packing density, reduced storage space, lightweight makes them ideal for miniature applications. This LED is 3.2 x 1.0mm, Red & Yellow green, Right Angle SMD LED, RoHS & REACH Compliant, and Applications is

- Flat backlight for LCD's.
- Switches and symbols.
- Backlighting in dashboard.
- Indicator and backlight in telephone

General Specifications

LED Colour	Bi-Color, Red & Yellow green, SMD LED			
Dimensions	3.2 x 1.0mm, Right Angle SMD			

Mechanical Specifications





Electrical Specifications

Absolute Maximum Ratings at Ta=25℃

Parameters		Symbol	Max	Unit
Power Dissipation	Red	Pd	60	mW
1 ower Bleespatieri	Yellow Green	1 4	60	mW
Peak Forward Current(a)		IFP	100	mA
DC Forward Current (b)	Red	IF	25	mA
	Yellow Green	11	25	mA
Reverse Voltage		VR	5	V
Operating Temperature Range		Topr	-40°C to+80°C	
Storage Temperature Range		Tstg	-40°C to+85°C	
Soldering Temperature		Tstg	260°Cfor 5 Seconds	

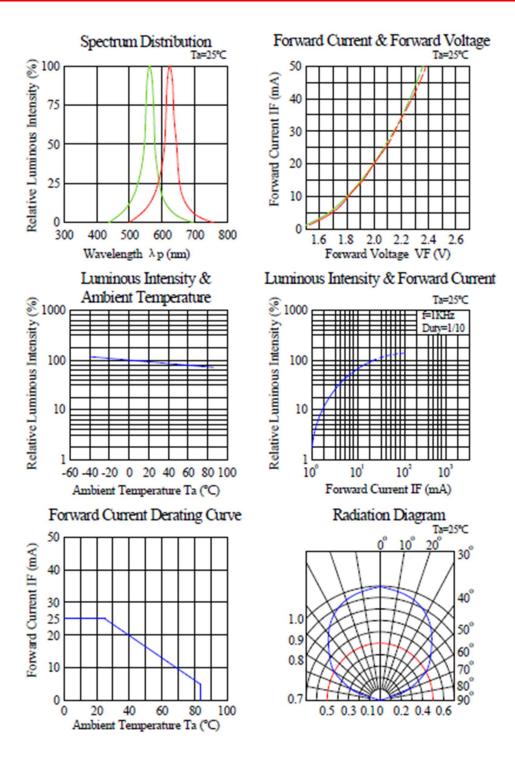
Electrical Optical Characteristics at Ta=25 ℃

Parameters	Symbol	Emitting Color	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity(a)	IV	Red	70	120		mcd	IF=20mA
		Yellow Green	30	50			
Viewing Angle	201/2	Red		120		Deg	IF=20mA
		Yellow Green		120			
Peak Emission Wavelength	λр	Red		632		nm	IF=20mA
		Yellow Green		575			
Dominant Wavelength	λd	Red		624		nm	IF=20mA
		Yellow Green		573			
	Δλ	Red		20		nm	IF=20mA
Spectral Line Half- Width		Yellow Green		20			
Forward Voltage Per Segment	VF	Red	1.6	2.0	2.4	V	IF=20mA
		Yellow Green	1.6	2.2	2.4		
Reverse Current Per Segment	IR -				10	μа	VR=5V
					10		



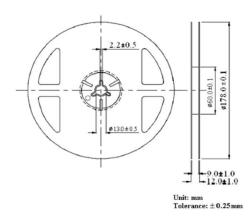
Typica IElectrical / Optical Characteristics Curves

(25 °C Ambient Temperature Unless Otherwise Noted)



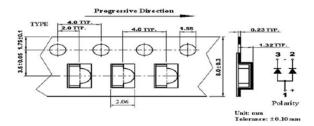


Reel Dimensions / Packing & Label Specifications:

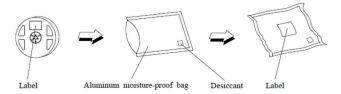


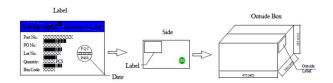
Carrier Tape Dimensions:

Loaded quantity 3000 pcs per reel.



Moisture Resistant Packaging:





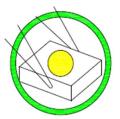


CAUTIONS

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1. Handling Precautions:

- 1.1. Handle the component along the side surfaces by using forceps or appropriate tools.
- 1.2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.
- 1.3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.









Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

2. Storage

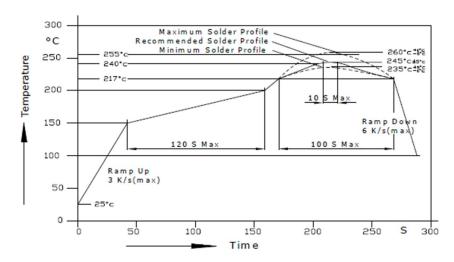
- 2.1. Do not open moisture proof bag before the products are ready to use.
- 2.2. Before opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.3. The LEDs should be used within a year.
- 2.4. After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5. The LEDs should be used within 24 hours after opening the package.
- 2.6. If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 65±5°C for 24 hours



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3. Soldering Condition

3.1. Pb-free solder temperature profile



- 3.2. Reflow soldering should not be done more than two times.
- 3.3. When soldering, do not put stress on the LEDs during heating.
- 3.4. After soldering, do not warp the circuit board.
- 3.5. Recommended soldering conditions:

Reflow soldering		Soldering iron			
Pre-heat	150~200°C	Temperature	300°C Max.		
Pre-heat time	120 sec. Max.	Soldering time	3 sec. Max.		
Peak temperature	260°C Max.		(one time only)		
Soldering time	10 sec. Max.(Max. two times)				

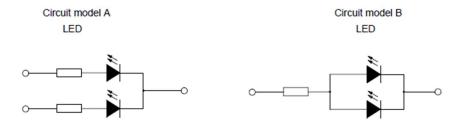
3.6. Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.



CAUTIONS

4. Drive Method

4.1. An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



- a. Recommended circuit.
- b. The brightness of each LED might appear different due to the differences in the I-V characteristics of those

5. ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Suggestions to prevent ESD damage:

- . Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- · All devices, equipment, and machinery must be properly grounded.
- · Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents. To verify for ESD damage, check for "lightup" and Vf of the suspect LEDs at low currents. The Vf of "good" LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AllnGaP product.